



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-11-24
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ESDA6V1LY	AJWC*EAY6V12	A	DIODES INC.	2016-11-24
	Amount	UoM	Unit type	ST ECOPACK Grade
	8.00	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Alloy 42		

Package Designator	Size	Nbr of instances	Shape	
DSO	2.9-1.625-1.175	6	gull wing	
Comment	SOT 23 SIMPLE DIODE			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	AJWC*EAY6V12					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.288	mg	supplier	die	Silicon (Si)	7440-21-3		0.285	mg	989583	35625
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	6944	250
				supplier	Passivation	Silicon Oxide	7631-86-9		0.001	mg	3473	125
Leadframe	Copper & its alloys	6.463	mg	supplier	alloy	Iron (Fe)	7439-89-6		3.662	mg	566610	457750
				supplier	alloy	Nickel (Ni)	7440-02-0		2.652	mg	410336	331500
				supplier	metallization	Silver (Ag)	7440-22-4		0.149	mg	23054	18625
Die attach	Other Organic Materials	0.142	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.106	mg	746479	13250
				supplier	glue or tape	Bis F Epoxy Resin	28064-14-4		0.021	mg	147887	2625
				supplier	glue or tape	1,4-bis(2,3-epoxypropoxy)butane	2425-79-8		0.011	mg	77465	1375
				supplier	glue or tape	Aromatic amine	Proprietary		0.004	mg	28169	500
Bonding wires	Other inorganic materials	0.048	mg	supplier	wire	Gold (Au)	7440-57-5		0.048	mg	1000000	6000
Encapsulation	Other Organic Materials	0.710	mg	supplier	mold compound	silica vitreous	60676-86-0		0.605	mg	852113	75625
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		0.039	mg	54930	4875
				supplier	mold compound	Phenol Resin	26834-02-6		0.036	mg	50704	4500
				supplier	mold compound	Tetrakis(2,6-dimethylphenyl) 1,3-phenylene bi	139189-30-3		0.018	mg	25352	2250
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.011	mg	15493	1375
				supplier	mold compound	Carbon black	1333-86-4		0.001	mg	1408	125
Connections coating	Solder	0.349	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.349	mg	1000000	43625